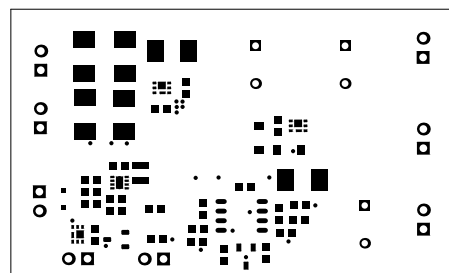
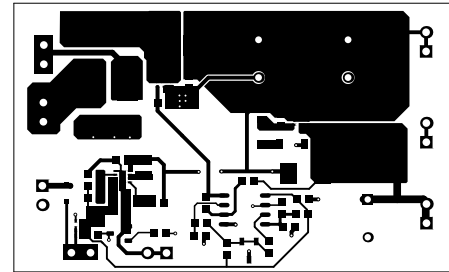


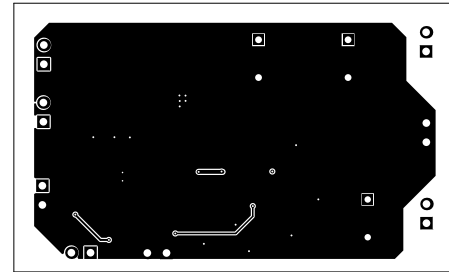
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01385	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01385		
PLOT NAME = Top Overlay	GENERATED : 5/18/2017 4:30:31 PM	TEXAS INSTRUMENTS	



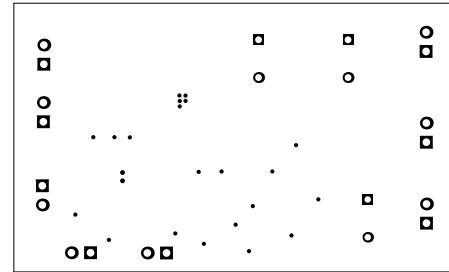
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01385	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01385		
PLOT NAME = Top Solder Mask	GENERATED : 5/18/2017 4:30:33 PM	TEXAS INSTRUMENTS	



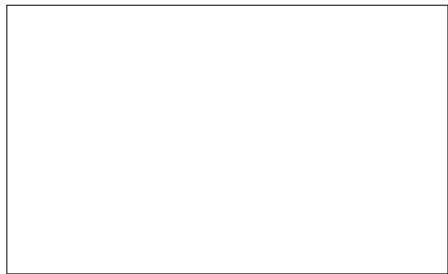
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01385	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01385		
PLOT NAME = Top Layer	GENERATED : 5/18/2017 4:30:35 PM	TEXAS INSTRUMENTS	



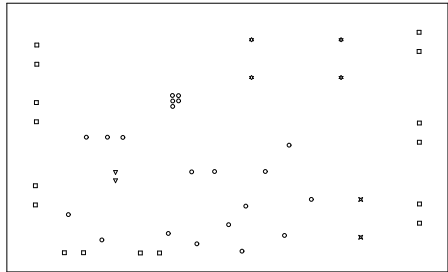
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01385	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01385		
PLOT NAME = Bottom Layer	GENERATED : 5/18/2017 4:30:36 PM	TEXAS INSTRUMENTS	



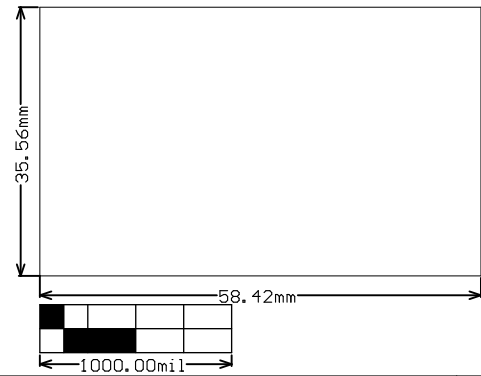
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01385	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01385		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/18/2017 4:30:38 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01385	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01385		
PLOT NAME = Bottom Overlay	GENERATED : 5/18/2017 4:30:40 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01385	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01385		
PLOT NAME = Drill Drawing	GENERATED : 5/18/2017 4:30:41 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01385	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01385		
PLOT NAME = Board Dimensions	GENERATED : 5/18/2017 4:30:43 PM	TEXAS INSTRUMENTS	

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